## EXPRESS MAIL LABEL NO. 516214648 US

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(Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) PATENT	
Tab settings ⇔⇔ ♥ ▼	▼
	Please record the attached original documents or copy thereof.
Name of conveying party(ies):	2. Name and address of receiving party(ies)
Chia-Lin Cheng	Name: Taiwan Semiconductor Manufacturing Co., Ltd.
E. J. Wu	Name. Tawan Commondation Mandiacturing Co., Etc.
Shih-Cherng Chang	Internal Address:
Kuo-Yin Chen	9.0
Additional name(s) of conveying party(es) attached? Yes No	<u></u>
3. Nature of conveyance:	<u></u>
✓ Assignment	2.5
Security Agreement Change of Name	Street Address: No. 8, Li-Hsin Road 6
Other	Science Based Industrial Park
	City:_Hsin-ChuState: Zip:
1, 3, & 4 - 3/15/05	Country: Taiwan 300-77 R.O.C.
Execution Date: 2-3/19/05	Additional name(s) & address(es) attached? Yes Vo
4. Application number(s) or patent number(s):	1, 3, & 4 - 3/15/05
If this document is being filed together with a new applica	0. 2/40/05
A. Patent Application No.(s)	B. Patent No.(s)
Additional numbers at	ached? Yes No
5. Name and address of party to whom correspondence	6. Total number of applications and patents involved:
concerning document should be mailed:  Name: Steven E. Koffs, Esquire	7. Total fee (37 CFR 3.41)\$ 40.00
Name: Oteven E. Rons, Esquire	
Internal Address: Duane Morris LLP	Enclosed
	Authorized to be charged to deposit account
	[V] The second of the second o
<del></del>	8. Deposit account number:
Street Address: One Liberty Place	
	04-1679
City: Philadelphia State: PA Zip: 19103	
DO NOT USE	THIS SPACE
9. Signature.	
Richard A. Paikoff	nd A. Parkoff 03/24/2005
Name of Person Signing	M. H. Valkeff         03/24/2005           Signature         Date
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Mail documents to be recorded with	sheet, attachments, and documents: 4
40.00 DA Commissioner of Patents & T	

Washington, D.C. 20231

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ATTORNEY DOCKET NO.: 2004.0613/1280.01260

## ASSIGNMENT AND AGREEMENT

For value received, we, Chia-Lin Cheng, I. Chieh Wu, Shih-Cherng Chang, and Kuo-Yin Chen, hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to METHOD FOR INTEGRALLY CHECKING CHIP AND PACKAGE SUBSTRATE LAYOUTS FOR ERRORS described in an application for Letters Patent of the United States and all the rights and privileges in said applications and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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PATENT REEL: 016420 FRAME: 0418 EXPRESS MAIL LABEL NO. EV 516214648 US

ATTORNEY DOCKET NO.: 2004.0613/1280.01260

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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